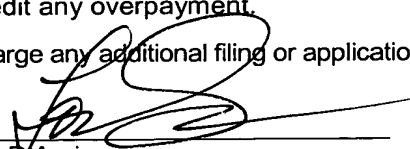


<b>AMENDMENT TRANSMITTAL LETTER</b>			Docket No. M4065.0226/P226	
Application No. 09/484,437-Conf. #9698	Filing Date January 18, 2000	Examiner J. M. Mitchell	Art Unit 2813	
Applicant(s): Tongbi Jiang				
Invention: DIE ATTACH CURING METHOD FOR SEMICONDUCTOR DEVICE				
<b>TO THE COMMISSIONER FOR PATENTS</b>				
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.				
<b>CLAIMS AS AMENDED</b>				
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate
<b>Total Claims</b>	33	- 33 =		x
<b>Independent Claims</b>	2	- 2 =		x
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>				
Other fee (please specify):				
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:</b>				0.00
<input checked="" type="checkbox"/> Large Entity <span style="margin-left: 200px;"><input type="checkbox"/> Small Entity</span>				
<input checked="" type="checkbox"/> No additional fee is required for this amendment.				
<input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of \$ _____. A duplicate copy of this sheet is enclosed.				
<input type="checkbox"/> A check in the amount of \$ _____ to cover the filing fee is enclosed.				
<input type="checkbox"/> Payment by credit card. Form PTO-2038 is attached.				
<input checked="" type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. <u>04-1073</u> as described below. A duplicate copy of this sheet is enclosed.				
<input checked="" type="checkbox"/> Credit any overpayment.				
<input checked="" type="checkbox"/> Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.				
 _____ Thomas J. D'Amico Attorney/Agent Reg. No.: 28,371			Dated: <u>June 12, 2006</u>	
DICKSTEIN SHAPIRO MORIN & OSHINSKY LP 2101 L Street NW Washington, DC 20037-1526 (202) 828-2232				



Docket No.: M4065.0226/P226  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor  
device

Examiner: J. M. Mitchell

**AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated January 11, 2006 (Part of Paper No. 122005), finally rejecting claims 1-3, 5-9, 11, 12, 14, 16-20 and 33-50, please consider the following Remarks.